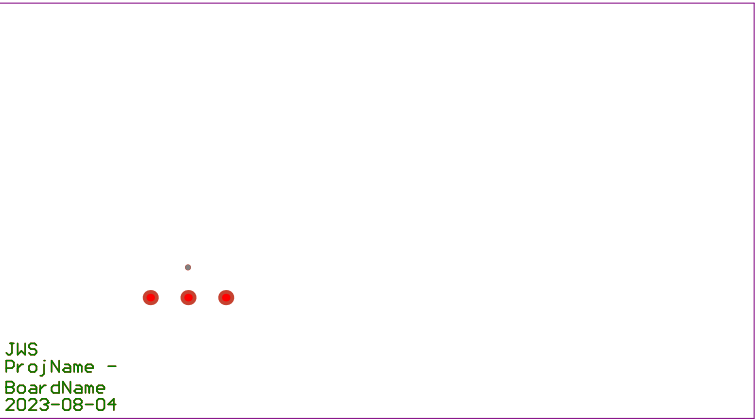




Top Assembly
Bottom Assembly

Outline



Top Layer

Top Paste

Top Solder

Top Courtyard

Top Overlay

Outline



Bottom Layer

Bottom Paste

Bottom Overlay
Outline



Fab Notes

Outline

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
□	1	0.350mm (13.78mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	1 Total						

1. PCB SHALL BE MANUFACTURED AS A 2 LAYER FR4 PCB.
2. ALL DIMENTIONS ARE IN mm UNLESS OTHERWISE SPECIFIED.
3. PCB SHALL BE MANUFACTURED TO MEET IPC-6012 CLASS 2.
4. SURFACE FINISH SHALL BE ENIG.
5. PCB MATERIAL TO BE 170 Tg FR4
6. SOLDERMASK BOTH SIDES OVER BARE COPPER, COLOR: GREEN.
7. PCB SHALL BE ROHS COMPLIANT.
8. MINIMUM COPPER WALL THICKNESS OF PLATED THROUGH HOLES SHALL BE 0.025mm WITH A MINIMUM ANNULAR RING OF 0.05mm.
9. TRACE WIDTH TOLERANCE SHALL BE +/-0.03mm.
10. COPPER SHALL BE PLATED TO A FINISHED THICKNESS OF 1-OZ.
11. SILKSCREEN SHALL BE APPLIED TO THE TOP SIDE, COLOR: WHITE.